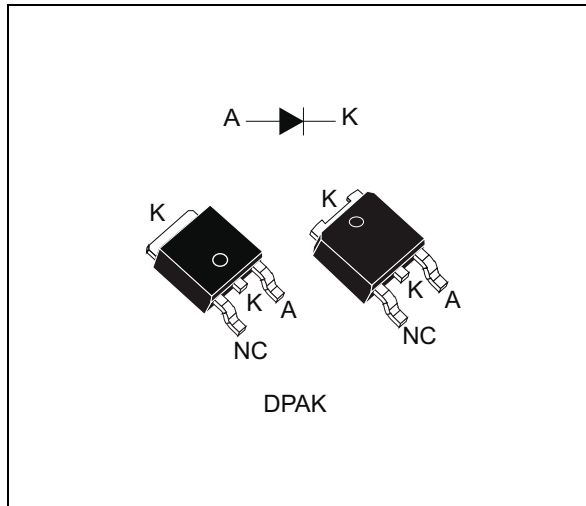


## Low drop power Schottky rectifier

Datasheet – production data


**Description**

Single Schottky rectifier suited for switch mode power supply and high frequency DC to DC converters.

Packaged in DPAK, this device is intended for use as a rectifier at the secondary of 3.3 V SMPS units.

**Table 1. Device summary**

Symbol	Value
$I_{F(AV)}$	5 A
$V_{RRM}$	25 V
$T_j(max)$	150 °C
$V_{F(typ)}$	0.31 V

**Features**

- Very low forward voltage drop for less power dissipation and reduced heatsink
- Optimized conduction/reverse losses trade-off which means the highest efficiency in the applications
- High power surface mount miniature package
- Avalanche specification
- ECOPACK<sup>®2</sup> compliant component for DPAK on demand

# 1 Characteristics

**Table 2. Absolute ratings (limiting values, at 25 °C unless otherwise stated)**

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage	25	V	
I <sub>F(RMS)</sub>	Forward rms current	7	A	
I <sub>F(AV)</sub>	Average forward current, $\bar{\delta} = 0.5$ square wave	T <sub>c</sub> = 140 °C,	5	A
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal	75	A
P <sub>ARM</sub>	Repetitive peak avalanche power	t <sub>p</sub> = 10 μs, T <sub>j</sub> = 125 °C	215	W
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C	
T <sub>j</sub>	Maximum operating junction temperature <sup>(1)</sup>	150	°C	

1.  $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistance**

Symbol	Parameter	Max. value	Unit
R <sub>th(j-c)</sub>	Junction to case	2.5	°C/W

**Table 4. Static electrical characteristics**

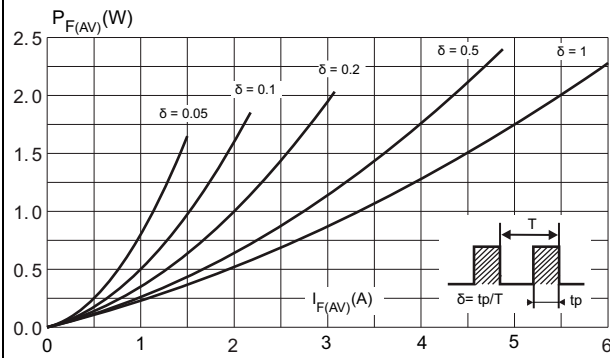
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit	
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	V <sub>R</sub> = V <sub>RRM</sub>	-	-	350	μA
		T <sub>j</sub> = 125 °C		-	55	115	mA
V <sub>F</sub> <sup>(1)</sup>	Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 5 A	-	-	0.47	V
		T <sub>j</sub> = 125 °C		-	0.31	0.35	
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 10 A	-	-	0.59	
		T <sub>j</sub> = 125 °C		-	0.41	0.50	

1. Pulse test: t<sub>p</sub> = 380 μs, δ < 2%

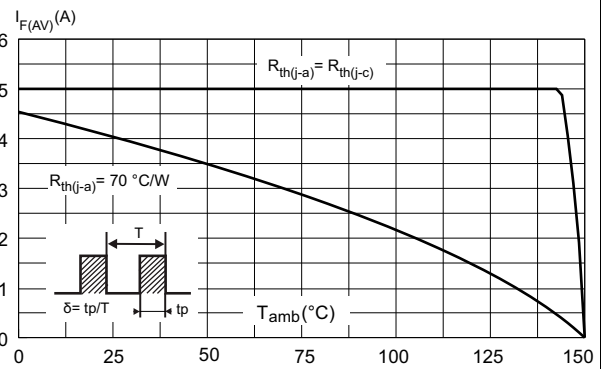
To evaluate the conduction losses use the following equation:

$$P = 0.2 \times I_{F(AV)} + 0.03 \times I_{F(RMS)}^2$$

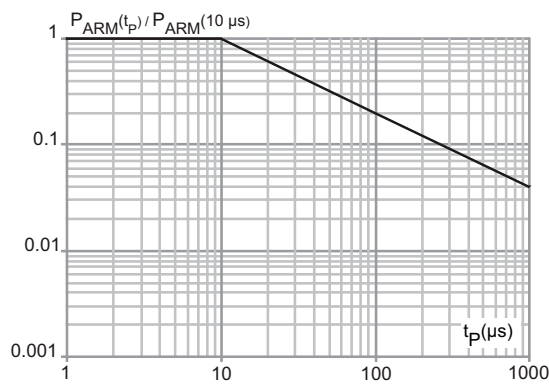
**Figure 1. Average forward power dissipation versus average forward current**



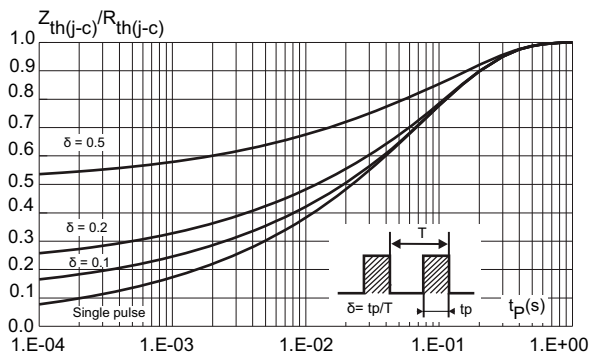
**Figure 2. Average forward current versus ambient temperature ( $\delta = 0.5$ )**



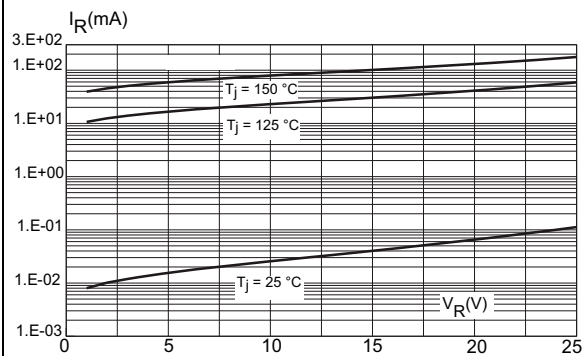
**Figure 3. Normalized avalanche power derating versus pulse duration at  $T_j = 125 \text{ } ^\circ\text{C}$**



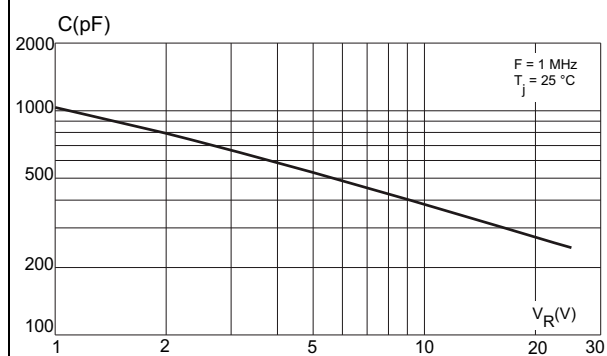
**Figure 4. Relative variation of thermal impedance junction to case versus pulse duration**



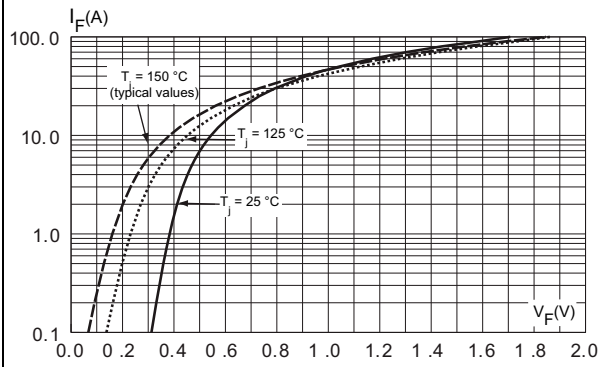
**Figure 5. Reverse leakage current versus reverse reverse voltage applied (typical values)**



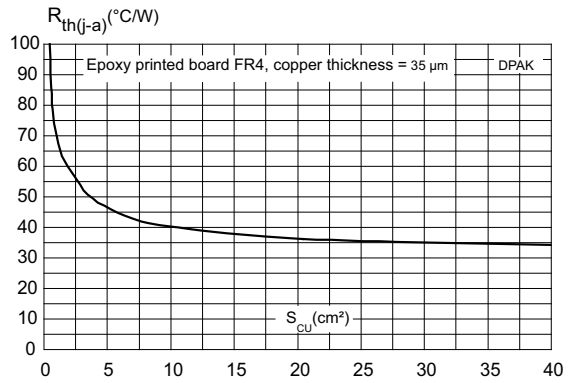
**Figure 6. Junction capacitance versus reverse voltage applied (typical values)**



**Figure 7. Forward voltage drop versus forward current (maximum values)**



**Figure 8. Thermal resistance junction to ambient versus copper surface under tab**



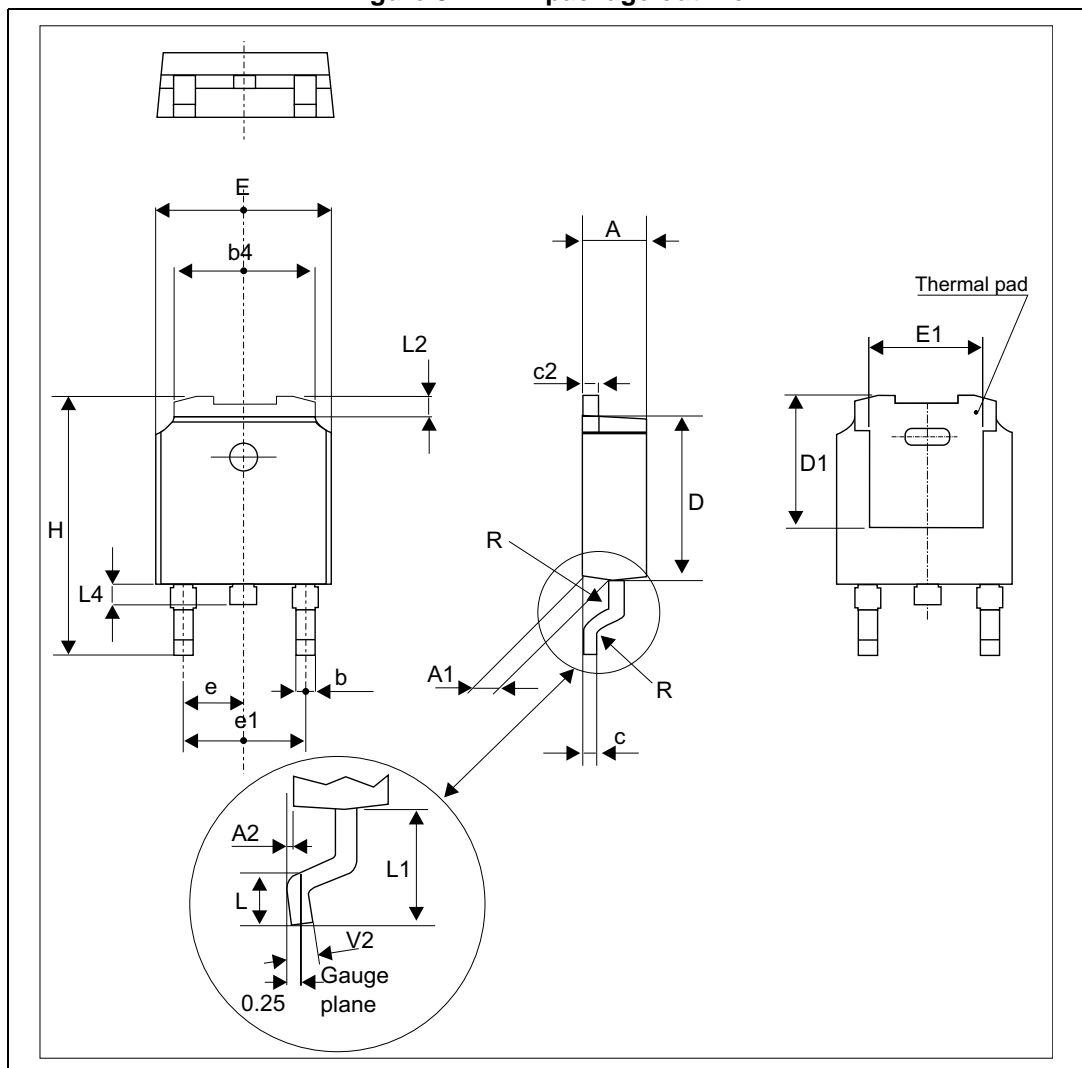
## 2 Package Information

- Epoxy meets UL94,V0
- Cooling method: by conduction (C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

### 2.1 DPAK package information

Figure 9. DPAK package outline

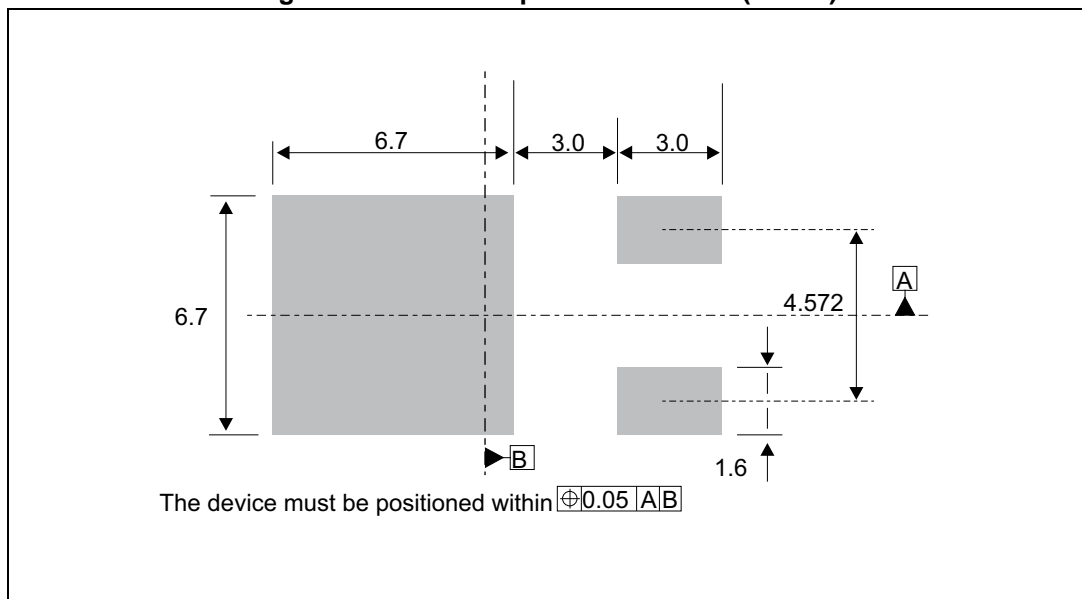


**Note:** This package drawing may slightly differ from the physical package. However, all the specified dimensions are guaranteed.

Table 5. DPAK package mechanical data

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.18		2.40	0.085		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
b	0.64		0.90	0.025		0.035
b4	4.95		5.46	0.194		0.214
c	0.46		0.61	0.018		0.024
c2	0.46		0.60	0.018		0.023
D	5.97		6.22	0.235		0.244
D1	4.95		5.60	0.194		0.220
E	6.35		6.73	0.250		0.264
E1	4.32		5.50	0.170		0.216
e		2.28			0.090	
e1	4.40		4.70	0.173		0.185
H	9.35		10.40	0.368		0.409
L	1.00		1.78	0.039		0.070
L2			1.27			0.050
L4	0.60		1.02	0.023		0.040
V2	-8°		+8°	-8°		8°

Figure 10. DPAK footprint dimensions (in mm)



### 3 Ordering information

**Table 6. Ordering information**

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPS5L25B-TR	STPS5 L25B	DPAK	0.32 g	2500	Tape and reel

### 4 Revision history

**Table 7. Document revision history**

Date	Revision	Changes
Jul-2003	5A	Previous release.
15-Apr-2008	6	Reformatted to current standard. Corrected order code in <a href="#">Table 5</a> .
08-Jan-2015	7	Updated package information and reformatted to current standard.
15-May-2017	8	Updated DPAK package information and reformatted to current standard.

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